

**AMENDMENTS TO THE CLAIMS:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

**Listing Of Claims:**

1-8. (Canceled)

9. (New) A micromechanical component, comprising:

a body having a hollow space and a region of porous silicon located contiguously thereto, wherein the region of porous silicon is provided for lowering a pressure prevailing in the hollow space, in that gases are bound to the porous silicon.

10. (New) The component as recited in Claim 9, wherein the porous silicon binds oxygen by forming silicon dioxide already in response to a low temperature.

11. (New) The component as recited in Claim 9, further comprising:

a first substrate;

a second substrate; and

an intermediate layer provided between the first substrate and the second.

12. (New) The component as recited in Claim 11, wherein the first substrate and the second substrate are joined to one another in such a way that they are hermetically sealed at the intermediate layer.

13. (New) The component as recited in Claim 9, further comprising:

a first substrate; and

a membrane, wherein:

the hollow space is provided between the membrane and the first substrate, and

the region of porous silicon is provided in the first substrate.

14. (New) A method for manufacturing a component, comprising:

producing a micromechanical structure in a first substrate;

producing in a second substrate a region of porous silicon; and

joining the first substrate and the second substrate.

15. (New) A method for manufacturing a component, comprising:

producing a region of porous silicon in a first substrate;

producing in the first substrate a region of porous silicon; and  
joining a second substrate to the first substrate.

16. (New) A method for manufacturing a component, comprising:  
producing a region of porous silicon in a first substrate; and  
producing in the first substrate a region of porous silicon.
17. (New) The method as recited in Claim 14, further comprising:  
activating the region of porous silicon, thereby lowering a pressure.
18. (New) The method as recited in Claim 15, further comprising:  
activating the region of porous silicon, thereby lowering a pressure.
19. (New) The method as recited in Claim 16, further comprising:  
activating the region of porous silicon, thereby lowering a pressure.